22858 U.S. PTO 10/804254

PATENT APPLICATION



Mail Stop Patent Application Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed herewith for filing under the provisions of 37 C.F.R. \$1.53(b) is the following continuation application of the prior, co-pending application United States Patent Application Serial No. 10/039,907, filed January 2, 2002 by Stimson, et al., which is a continuation application of United States Patent Application Serial No. 09/182,023, filed October 29, 1998, and are herein incorporated into the present continuation application by reference in their entireties.

Applicant(s): Bradley O. Stimson
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Eric Delaurentis
Praburam Gopalraja
Patricia Rodriguez

Anantha Subramani

Title of application: PROCESS KIT FOR IMPROVED POWER COUPLING

THROUGH A WORKPIECE IN A SEMICONDUCTOR

WAFER PROCESSING SYSTEM

Pages of specification: 17 (4 pages of claims and 1 page

abstract)

Sheets of drawing: 4

Executed on: Docket No.: 1946C2/AGS/IBSS/LP

m 1	PATENT APPLICA	ATION FII Less		FEE CALCULA /Claim	ATION Fee	
Total Claims	20	-20	0	x \$18.00	\$ 0	.00
Independent Claims	3	- 3	0	x \$86.00	\$ 0	.00
	Minimu	ım Filinç	g Fee	·	\$770	.00
		ole Deper oplicable			\$	

50% Reduction for Small Entity (Independent Inventor, Non-profit Corporation, or Small Business Concern) - appropriate

verified statement attached

- \$ 0.00

Assignment Recordation Fee

\$ 40.00

TOTAL FILING FEE

\$810.00

Kindly charge the entire and any additional filing fee, as appropriate, to Deposit Account No. 20-0782. To facilitate that charge, a duplicate copy of this letter is enclosed herewith.

Kindly direct all correspondence to:

Patent Counsel Applied Materials, Inc. 3050 Bowers Avenue P.O. Box 450A Santa Clara, CA 95052

Also enclosed herewith for filing in connection with the enclosed application are:

- A copy of the executed Declaration of the prior application 09/182,023 from the co-inventors to Applied Materials, Inc., which remains in effect for the subject continuation application
- Claim(s) to priority under 35 U.S.C. §120: X Serial Number Filing date 10/039,907 January 2, 2002 09/182,023 October 29, 1998
- Χ_ The above-identified prior application (10/039,907) is co-pending.
- The Assignment of the prior application 09/182,023 from the co-inventors to Applied Materials, Inc., which remains in effect for the subject divisional application
- X 4 sheets of formal drawings.

Respectfully submitted,

March 19204

KEITH TABOADA, Attorney

Req. No. 45,150

EXPRESS MAIL CERTIFICATION

"Express Mail" mailing label number: EV360627127US Date of deposit: March 19, 2004
Date of deposit: March 19, 2004
I hereby certify that this patent application and relate papers is being deposited with the United States Postal Servic "Express Mail Post Office to Addressee" service under 37 C.F.R 1.10 on the date indicated above and is addressed to Mail Sto Patent Application, Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-14150.
Signature of person mailing paper or fee
signature of person mailing paper of fee
Allyson M. DeVesty
Name of person mailing paper or fee